

Technical data sheet

SMC 3381 RF

SMC 3381 RF is a sheet moulding compound based on an unsaturated polyester resin, fire retardant grade, halogen-free, reinforced with glass fibres. This SMC has been developed for electrical application. **SMC 3381 RF** joint good mechanical properties and good fire protection grade.

SMC 3381 RF complies with UNI CEI 11170-3. **SMC 3381 RF** is formulated according to RoHS, REAC regulation (SVHC) and WEEE European legislation.

Material code ISO 11469 > UP-(MD+GF)65FR(60) <

Typical material properties

CHARACTERISTICS	METHOD	UNIT	VALUE
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Quantity of glass	ISO 11667	%	25
Linear shrinkage	ISO 2577	%	0,1
Density	ISO 1183	g/cm ³	1,75
Water absorption	ISO 62 Met. 1	%	<u><</u> 0,2
Flexural strength	ISO 14125A	MPa	150
Flexural modulus	ISO 14125A	MPa	9.500
Impact strength (Charpy)	ISO 179	KJ/m ²	70
Rockwell hardness	ISO 2039-2	HRm	80
Heat distortion temperature HDT	ISO 75	°C	<u>></u> 200
Surface resistivity	IEC 93	Ω	10 ¹⁴
Volume resistivity	IEC 93	Ω mm	10 ¹⁴
Dielectric rigidity	IEC 243	KV/mm	18
Arc resistance	ASTM D 495	S	<u>></u> 180
Ignitability to direct impingement of flame	ISO 11925-2	30 s	Fs <u><</u> 150 mm
Reaction to fire	NF F 16-101	Class	12
Smoke index	NF F 16-101	Class	F1
Glow wire GWFI	IEC 695-2-1	°C	960
Flammability	UL 94	Class / mm	V0/3,0

Properties were determined on compression-moulded specimens according UNIPLAST rules project 412 and 413





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Storage and processing conditions

Storage at 15-25°C, in dry ambient and out of direct sun light

Moulding time 40 s/mm
Moulding pressure 70 - 110 bar
Moulding temperature 140 - 160°C

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